

### HIGH AND LOW SIDE DRIVER

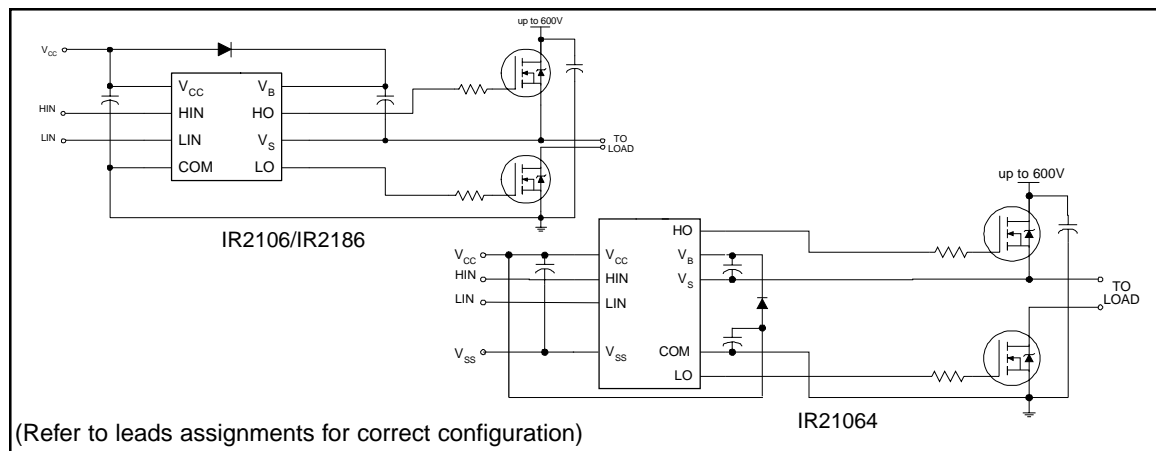
#### Features

- Floating channel designed for bootstrap operation  
Fully operational to +600V  
Tolerant to negative transient voltage  
dV/dt immune
- Gate drive supply range from 10 to 20V (IR2106(4))  
or 6 to 20V (IR2186)
- Undervoltage lockout for both channels
- 3.3V, 5V and 15V input logic compatible
- Matched propagation delay for both channels
- Logic and power ground +/- 5V offset.
- Lower di/dt gate driver for better noise immunity
- Outputs in phase with inputs (IR2106/IR2186)

#### Description

The IR2106/IR2186 are high voltage, high speed power MOSFET and IGBT drivers with independent high and low side referenced output channels. Proprietary HVIC and latch immune CMOS technologies enable ruggedized monolithic construction. The logic input is compatible with standard CMOS or LSTTL output, down to 3.3V logic. The output drivers feature a high pulse current buffer stage designed for minimum driver cross-conduction. The floating channel can be used to drive an N-channel power MOSFET or IGBT in the high side configuration which operates up to 600 volts.

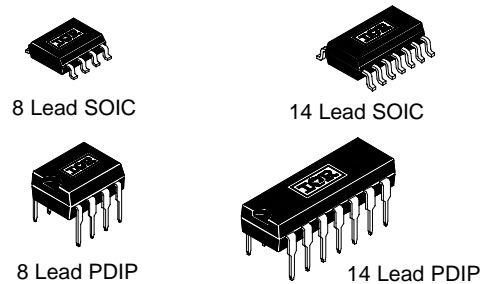
#### Typical Connection



#### Product Summary

$V_{\text{OFFSET}}$	600V max.	
$I_{\text{O}+/-}$	120 mA / 250 mA	
$V_{\text{OUT}}$	10 - 20V (IR2106(4))	7 - 20V (IR2186)
$t_{\text{on/off}}$ (typ.)	180 ns	
Delay matching	50 ns	

#### Packages



# IR2106/IR21064/IR2186 (S)

International  
 Rectifier

## Absolute Maximum Ratings

Absolute maximum ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions.

Symbol	Definition	Min.	Max.	Units	
V <sub>B</sub>	High side floating absolute voltage	-0.3	625	V	
V <sub>S</sub>	High side floating supply offset voltage	V <sub>B</sub> - 25	V <sub>B</sub> + 0.3		
V <sub>HO</sub>	High side floating output voltage	V <sub>S</sub> - 0.3	V <sub>B</sub> + 0.3		
V <sub>CC</sub>	Low side and logic fixed supply voltage	-0.3	25		
V <sub>LO</sub>	Low side output voltage	-0.3	V <sub>CC</sub> + 0.3		
V <sub>IN</sub>	Logic input voltage	V <sub>SS</sub> - 0.3	V <sub>CC</sub> + 0.3		
V <sub>SS</sub>	Logic ground (IR21064 only)	V <sub>CC</sub> - 25	V <sub>CC</sub> + 0.3		
dV <sub>S</sub> /dt	Allowable offset supply voltage transient	—	50	V/ns	
P <sub>D</sub>	Package power dissipation @ T <sub>A</sub> ≤ +25°C	(8 lead PDIP)	—	1.0	W
		(8 lead SOIC)	—	0.625	
		(14 lead PDIP)	—	1.6	
		(14 lead SOIC)	—	1.0	
R <sub>thJA</sub>	Thermal resistance, junction to ambient	(8 lead PDIP)	—	125	°C/W
		(8 lead SOIC)	—	200	
		(14 lead PDIP)	—	75	
		(14 lead SOIC)	—	120	
T <sub>J</sub>	Junction temperature	—	150	°C	
T <sub>S</sub>	Storage temperature	-50	150		
T <sub>L</sub>	Lead temperature (soldering, 10 seconds)	—	300		

**IR2106/IR21064/IR2186 (S)****Recommended Operating Conditions**

The Input/Output logic timing diagram is shown in figure 1. For proper operation the device should be used within the recommended conditions. The  $V_S$  and  $V_{SS}$  offset rating are tested with all supplies biased at 15V differential.

Symbol	Definition	Min.	Max.	Units
V <sub>B</sub>	High side floating supply absolute voltage			V
	IR2106(4)	$V_S + 10$	$V_S + 20$	
	IR2186	$V_S + 7$	$V_S + 20$	
V <sub>S</sub>	High side floating supply offset voltage	Note 1	600	
V <sub>HO</sub>	High side floating output voltage	$V_S$	$V_B$	
V <sub>CC</sub>	Low side and logic fixed supply voltage			
	IR2106(4)	10	20	
	IR2186	6	20	
V <sub>LO</sub>	Low side output voltage	0	$V_{CC}$	
V <sub>IN</sub>	Logic input voltage	$V_{SS}$	$V_{CC}$	
V <sub>SS</sub>	Logic ground (IR21064 only)	-5	5	
T <sub>A</sub>	Ambient temperature	-40	125	°C

Note 1: Logic operational for  $V_S$  of -5 to +600V. Logic state held for  $V_S$  of -5V to  $-V_{BS}$ .

**Dynamic Electrical Characteristics**

$V_{BIAS}$  ( $V_{CC}$ ,  $V_{BS}$ ) = 15V,  $V_{SS}$  = COM,  $C_L$  = 1000 pF,  $T_A$  = 25°C.

Symbol	Definition	Min.	Typ.	Max.	Units	Test Conditions
t <sub>on</sub>	Turn-on propagation delay	—	180	270	nsec	$V_S = 0V$
t <sub>off</sub>	Turn-off propagation delay	—	170	250		$V_S = 0V$ or 600V
MT	Delay matching, HS & LS turn-on/off	—	0	50		
t <sub>r</sub>	Turn-on rise time	—	150	220		$V_S = 0V$
t <sub>f</sub>	Turn-off fall time	—	50	80		$V_S = 0V$

# IR2106/IR21064/IR2186 (S)

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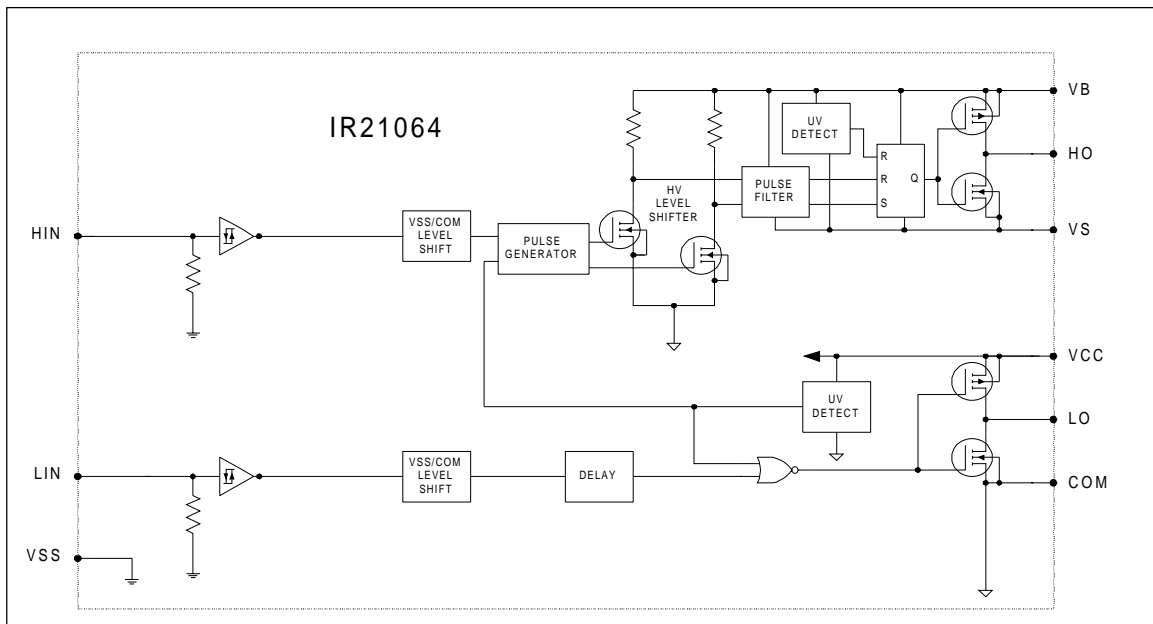
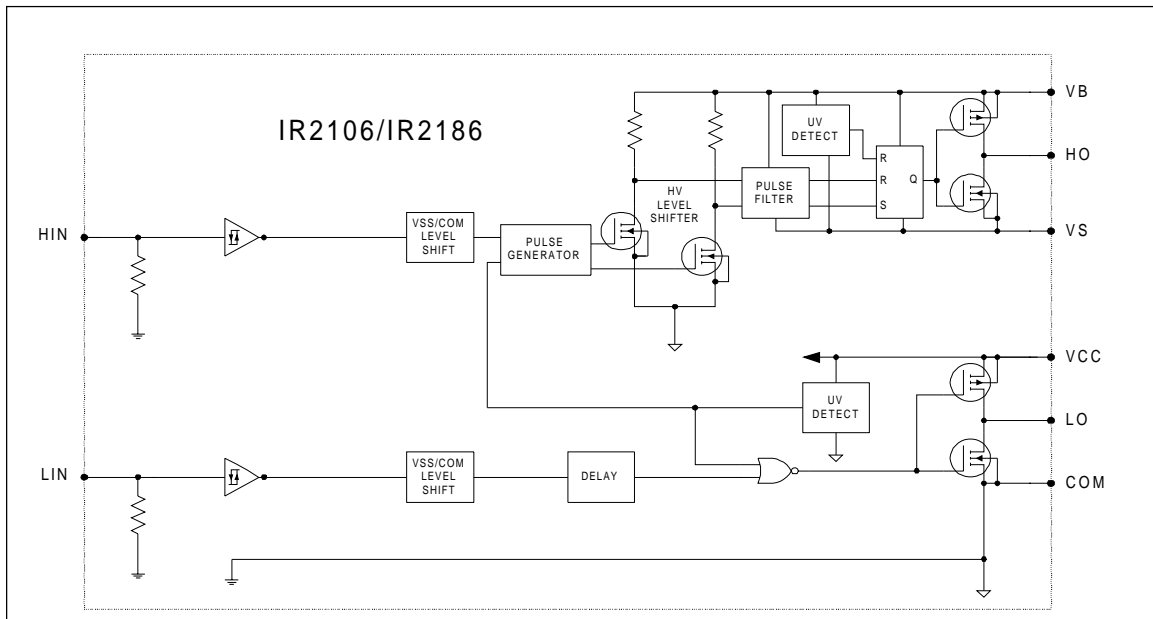
## Static Electrical Characteristics

$V_{BIAS}$  ( $V_{CC}$ ,  $V_{BS}$ ) = 15V,  $V_{SS}$  = COM and  $T_A$  = 25°C unless otherwise specified. The  $V_{IL}$ ,  $V_{IH}$  and  $I_{IN}$  parameters are referenced to  $V_{SS}/COM$  and are applicable to the respective input leads. The  $V_O$ ,  $I_O$  and  $R_{on}$  parameters are referenced to COM and are applicable to the respective output leads: HO and LO.

Symbol	Definition	Min.	Typ.	Max.	Units	Test Conditions	
$V_{IH}$	Logic "1" input voltage (IR2106(4)/IR2186)	2.7	—	—	V	$V_{CC} = 10V$ to 20V	
$V_{IL}$	Logic "0" input voltage (IR2106(4)/IR2186)	—	—	0.8		$V_{CC} = 10V$ to 20V	
$V_{OH}$	High level output voltage, $V_{BIAS} - V_O$	—	0.8	1.4		$I_O = 20$ mA	
$V_{OL}$	Low level output voltage, $V_O$	—	0.3	0.6		$I_O = 20$ mA	
$I_{LK}$	Offset supply leakage current	—	—	50	μA	$V_B = V_S = 600V$	
$I_{QBS}$	Quiescent $V_{BS}$ supply current	20	60	150		$V_{IN} = 0V$ or 5V	
$I_{QCC}$	Quiescent $V_{CC}$ supply current	50	120	240		$V_{IN} = 0V$ or 5V	
$I_{IN+}$	Logic "1" input bias current $V_{IN} = 5V$ (IR2106(4)/IR2186)	—	5	20			
$I_{IN-}$	Logic "0" input bias current $V_{IN} = 0V$ (IR2106(4)/IR2186)	—	1	2			
$V_{CCUV+}$	$V_{CC}$ supply undervoltage positive going threshold (IR2106(4)) (IR2186)	8.0 4.5	8.9 5.2	9.8 5.9	V		
$V_{CCUV-}$	$V_{CC}$ supply undervoltage positive going threshold (IR2106(4)) (IR2186)	7.4 4.1	8.2 4.8	9.0 5.5			
$V_{BSUV+}$	$V_{BS}$ supply undervoltage negative going threshold (IR2106(4)) (IR2186)	8.0 5.5	8.9 6.2	9.8 6.9			
$V_{BSUV-}$	$V_{BS}$ supply undervoltage negative going threshold (IR2106(4)) (IR2186)	7.4 5.1	8.2 5.8	9.0 6.5			
$V_{CCUVH}$	Hysteresis (IR2106(4))	0.3	0.7	—			
$V_{BSUVH}$	Hysteresis (IR2186)	0.1	0.4	—			
$I_{O+}$	Output high short circuit pulsed current	120	200	—		mA	$V_O = 0V$ , $PW \leq 10 \mu s$
$I_{O-}$	Output low short circuit pulsed current	250	350	—			$V_O = 15V$ , $PW \leq 10 \mu s$

# IR2106/IR21064/IR2186 (S)

## Functional Block Diagrams



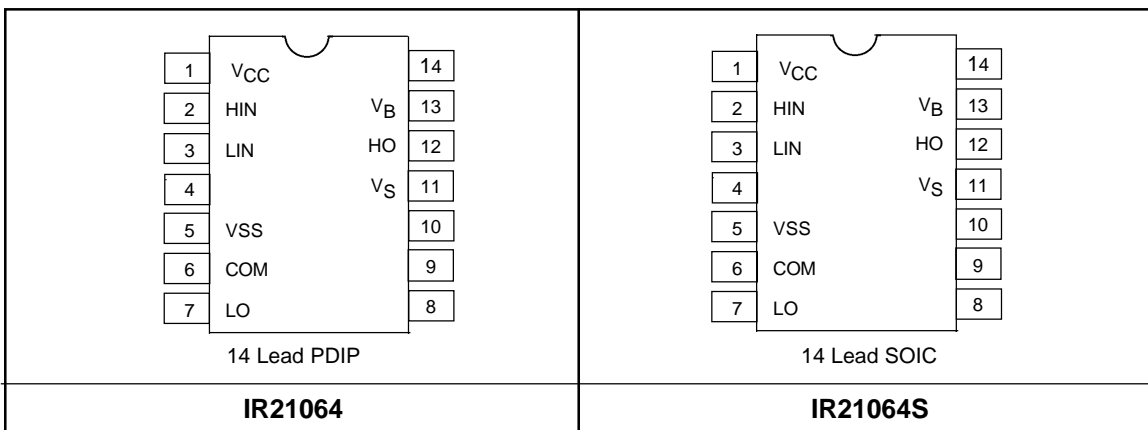
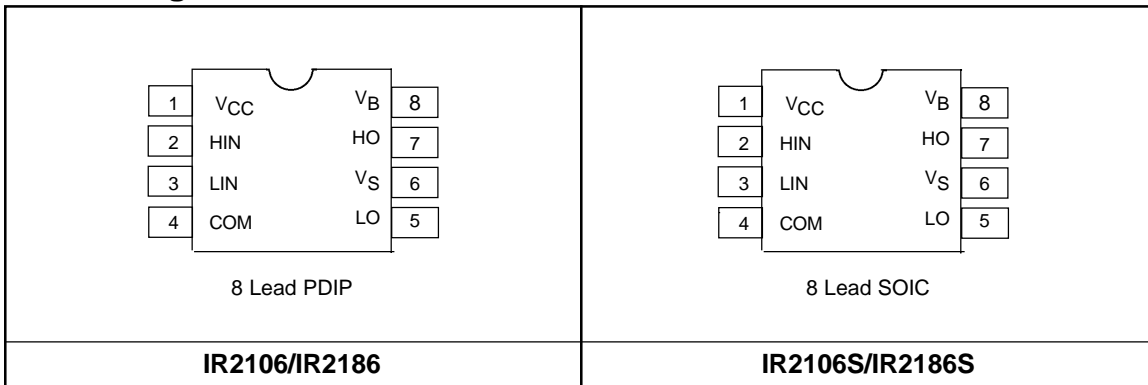
# IR2106/IR21064/IR2186 (S)

International  
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## Lead Definitions

Symbol	Description
HIN	Logic input for high side gate driver output (HO), in phase (IR2106(4)/IR2186)
LIN	Logic input for low side gate driver output (LO), in phase (IR2106(4)/IR2186)
VSS	Logic Ground (IR21064 only)
V <sub>B</sub>	High side floating supply
HO	High side gate drive output
V <sub>S</sub>	High side floating supply return
V <sub>CC</sub>	Low side and logic fixed supply
LO	Low side gate drive output
COM	Low side return

## Lead Assignments



# IR2106/IR21064/IR2186 (S)

## Case Outlines

Technical drawing of an 8 Lead PDIP package. The top view shows a rectangular body with 8 leads on each side, numbered 1-8. Dimensions include: total width 10.92 [.430] (controlling dimension 6), lead width 8.84 [.348] (controlling dimension 6), body width 7.11 [.280], body height 6.10 [.240], lead height 1.77 [.070], and lead thickness 1.15 [.045]. The side view shows a lead height of 5.33 [.210] MAX and a lead thickness of 0.39 [.015] MIN. The lead pitch is 2.54 [.100] (6X). The lead diameter is 0.25 [.010] (controlling dimension 5). The lead angle is 8X 0° - 15°. The lead length is 7.62 [.300] (controlling dimension 5). The lead thickness is 0.381 [.015] and 0.204 [.008].

NOTES:

1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M-1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-001AB.
- 5 MEASURED WITH THE LEADS CONSTRAINED TO BE PERPENDICULAR TO DATUM PLANE C.
- 6 DIMENSION DOES NOT INCLUDE MOLD PROTUSIONS. MOLD PROTUSIONS SHALL NOT EXCEED 0.25 [.010].

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### 8 Lead PDIP

Technical drawing of an 8 Lead SOIC package. The top view shows a rectangular body with 8 leads on each side, numbered 1-8. Dimensions include: total width D, lead width B, body width H, lead height A, and lead thickness E. The lead pitch is 2.54 [.100] (6X). The lead diameter is 0.25 [.010] (controlling dimension 5). The lead angle is 8X 0° - 15°. The lead length is 7.62 [.300] (controlling dimension 5). The lead thickness is 0.381 [.015] and 0.204 [.008].

RECOMMENDED FOOTPRINT

Technical drawing of the recommended footprint for the 8 Lead SOIC package. Dimensions include: lead pitch 8X 0.72 [.028], lead width 6.46 [.255], lead length 8X 1.78 [.070], and lead thickness 0.27 [.050].

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
b	.014	.018	0.36	0.46
c	.0075	.0098	0.19	0.25
D	.189	.196	4.80	4.98
E	.150	.157	3.81	3.99
e	.050 BASIC		1.27 BASIC	
e1	.025 BASIC		0.635 BASIC	
H	.2284	.2440	5.80	6.20
K	.011	.019	0.28	0.48
L	.016	.050	0.41	1.27
y	0°	8°	0°	8°

NOTES:

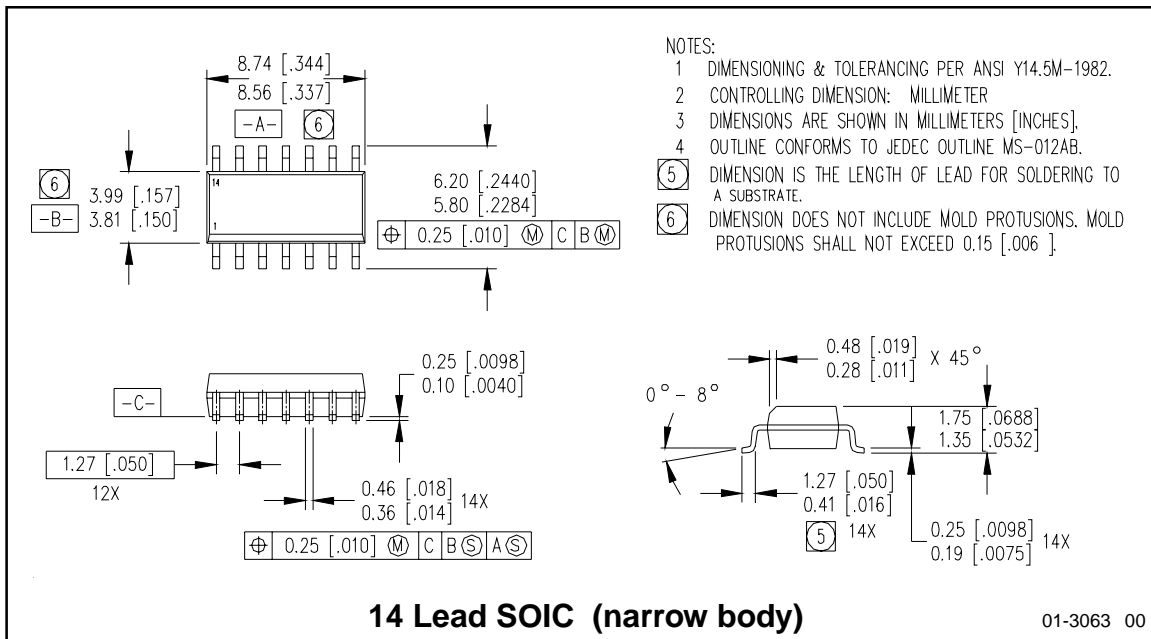
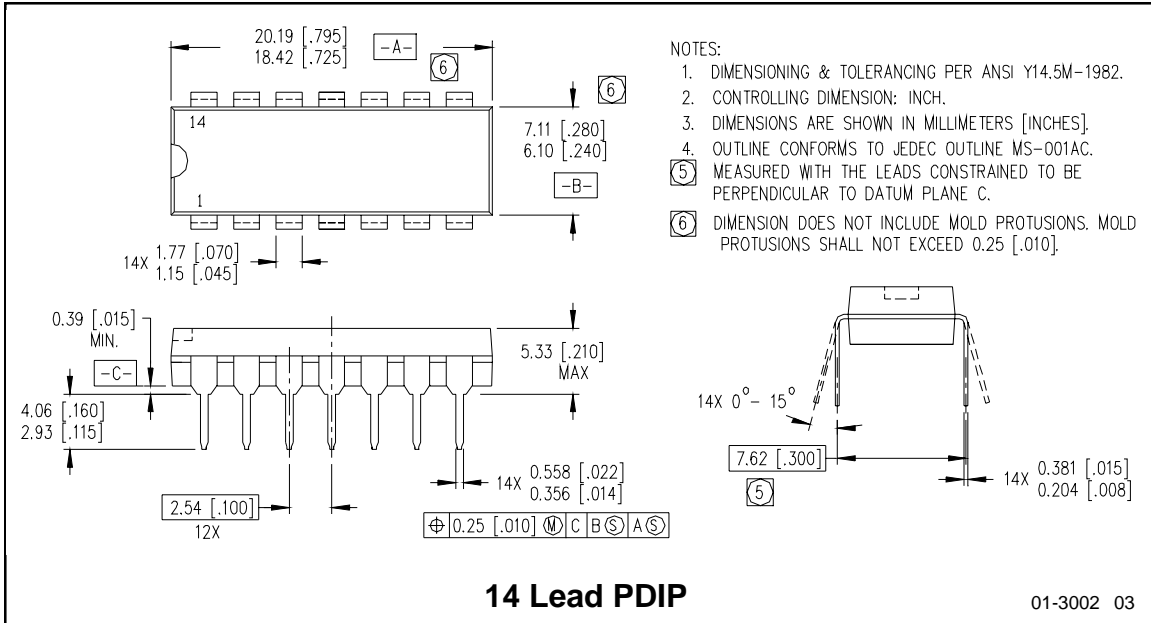
1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
- 5 DIMENSION DOES NOT INCLUDE MOLD PROTUSIONS. MOLD PROTUSIONS NOT TO EXCEED 0.25 [.006].
- 6 DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.

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### 8 Lead SOIC

# IR2106/IR21064/IR2186 (S)

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# IR2106/IR21064/IR2186 (S)

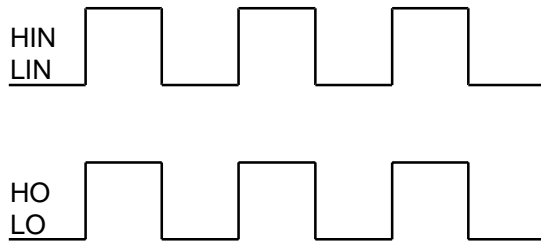


Figure 1. Input/Output Timing Diagram

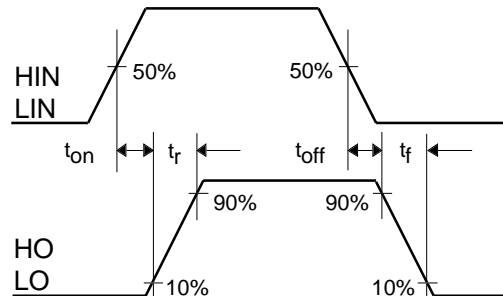


Figure 2. Switching Time Waveform Definitions

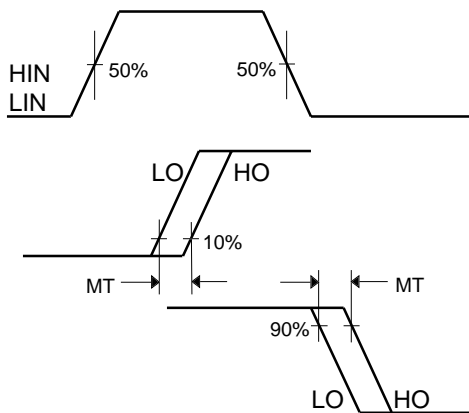


Figure 3. Delay Matching Waveform Definitions